

L Number	Hits	Search Text	DB	Time stamp
1	1	("20030030084").PN.	USPAT; US-PGPUB	2003/06/13 16:09
2	33869	sem or "scanning electron microscope"	USPAT; US-PGPUB	2003/06/13 16:09
3	466764	semiconductor or "integrated circuit" or microelectronic or IC	USPAT; US-PGPUB	2003/06/13 16:12
4	939	(sem or "scanning electron microscope") with (semiconductor or "integrated circuit" or microelectronic or IC)	USPAT; US-PGPUB	2003/06/13 16:12
5	745129	intermediate	USPAT; US-PGPUB	2003/06/13 16:12
6	5	((sem or "scanning electron microscope") with (semiconductor or "integrated circuit" or microelectronic or IC)) with intermediate	USPAT; US-PGPUB	2003/06/13 16:14
7	308469	testing	USPAT; US-PGPUB	2003/06/13 16:14
8	33	testing with ((sem or "scanning electron microscope") with (semiconductor or "integrated circuit" or microelectronic or IC))	USPAT; US-PGPUB	2003/06/13 16:23
9	68756	cmp or polishing	USPAT; US-PGPUB	2003/06/13 16:23
10	354271	trench or recess	USPAT; US-PGPUB	2003/06/13 16:23
11	13814	conformal	USPAT; US-PGPUB	2003/06/13 16:24
12	43	(cmp or polishing) with (trench or recess) with conformal	USPAT; US-PGPUB	2003/06/13 16:24
-	65379	438/\$.ccls.	USPAT; US-PGPUB	2003/06/01 18:14
-	463378	semiconductor or ic or "integrated circuit" or microelectronic	USPAT; US-PGPUB	2003/05/29 17:11

→ protecting / protect\$3 with CMP

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11	13814	conformal	USPAT; US-PGPUB	2003/06/13 16:24
12	43	(cmp or polishing) with (trench or recess) with conformal	USPAT; US-PGPUB	2003/06/13 16:39
13	2296	protect\$3 with (cmp or polishing)	USPAT; US-PGPUB	2003/06/13 16:40
14	1443	(semiconductor or "integrated circuit" or microelectronic or IC) and (protect\$3 with (cmp or polishing))	USPAT; US-PGPUB	2003/06/13 16:40
15	687	(trench or recess) and ((semiconductor or "integrated circuit" or microelectronic or IC) and (protect\$3 with (cmp or polishing)))	USPAT; US-PGPUB	2003/06/13 16:40
16	139	conformal and ((trench or recess) and ((semiconductor or "integrated circuit" or microelectronic or IC) and (protect\$3 with (cmp or polishing))))	USPAT; US-PGPUB	2003/06/13 16:40
-	65379	438/\$.ccls.	USPAT; US-PGPUB	2003/06/01 18:14
-	463378	semiconductor or ic or "integrated circuit" or microelectronic	USPAT; US-PGPUB	2003/05/29 17:11